

ABSTRACT

A semiconductor fabricating device and method that minimize the influence of a process deteriorating material that is generated during first processes on second processes, when the plurality of processes are continually performed step by step. Operational failures are prevented during the course of the semiconductor fabricating processes, by directing air flow from a location where the second processes are carried out to a location where the first processes are carried out, to carry the process deteriorating gas away from the second processes. This reduces the frequency of failures during processing.